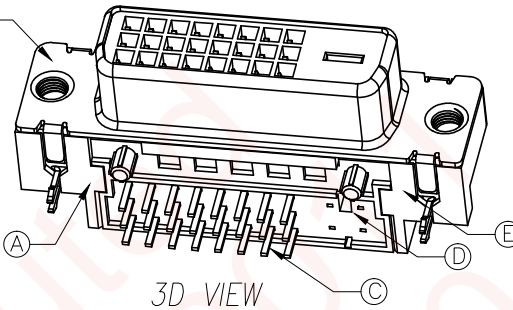


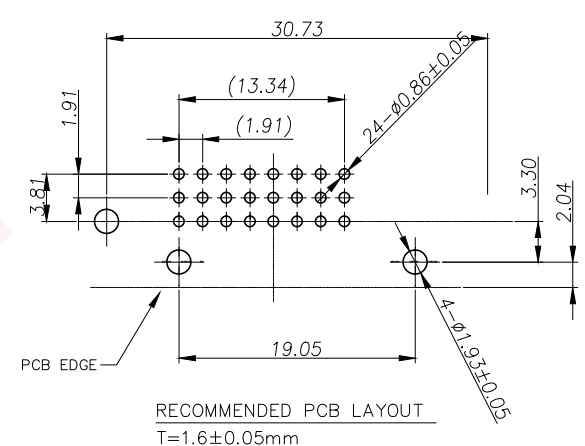
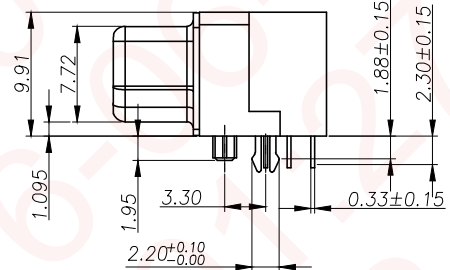
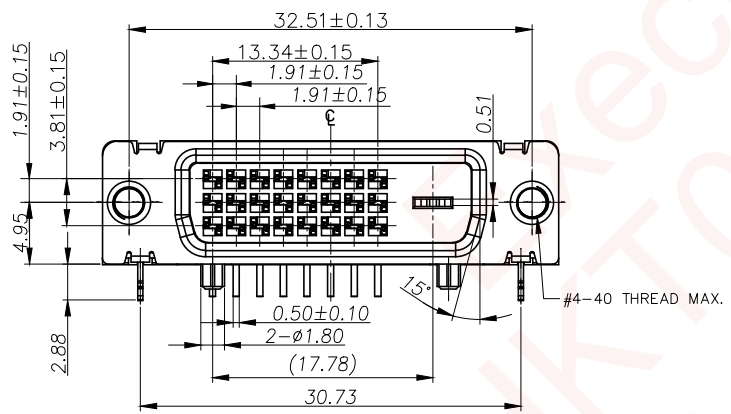
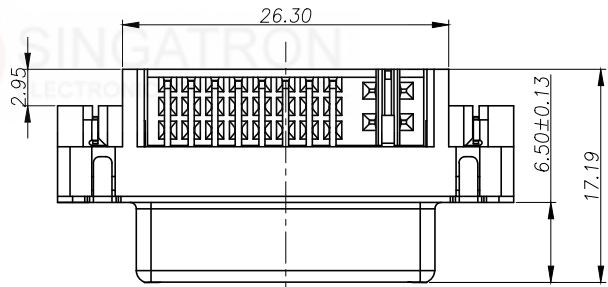
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO:S160408-8A	JTTLUCKY	2016.06.23

NOTE:

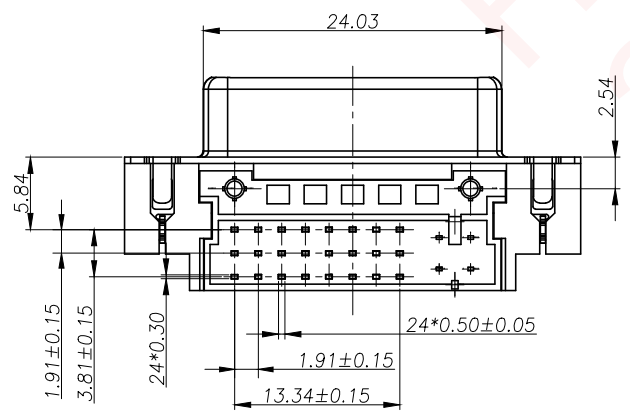
- MATERIAL:
  - INSULATOR: HIGH TEMPERATURE+30%GLASS FIRBE UL94V-0
  - TERMINAL: COPPER ALLOY
  - TERMINAL PLATING: SELECTIVE GOLG PLATING ON AREA.
  - TIN 100U"MIN.ON SOLDER TAIL.
  - SEHLL: SPCC-SD NICKEL PLATING.
  - GROUNDING CLIP: BRASS TIN PALTING.
  - NUT: COPPER ALLOY. NICKEL PLATING.
- ELECTRICAL:
  - INSULATOR RESISTANCE: 1000MEG OHMS MIN.
  - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC RMS.
  - VOLTAGE TATING: 40V AC RMS.CONTINUOUS MAX.
  - CURRENT RATING: 1.5A MIN. 3.0A MAX.
  - CONTACT RESISTANCE: 30 MILLLOHMS MAX.
- ENVIRONMENTAL
  - TEMPERATURE RANGE: -20°C TO +85°C.



3D VIEW



RECOMMENDED PCB LAYOUT  
T=1.6±0.05mm



E	BoardLock	2	Alloy	NICKEL and NIN MIN 60u"MIN
D	COVER	1	PBT	BLACK
C	TERMINAL	24	COPPER ALLOY T=0.30	G/F Au ON MATING AREA, 100u"MIN IN PLATED ON SOLDERING 50u"NICKEL UNDER PLATING OVERALL
B	SHELL	1	SPCC T=0.50	NICKEL 60u"MIN
A	HOUSING	1	HIGH TEMPERATURE	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司		
DECIMALS:		TITLE		
X	:±0.5	X	:±1°	DVI 单层24+1
X.X	:±0.3	X.X	:±0.5°	DWN jttlucky PART NO. 2DS3Y49-025112H
X.XX	:±0.2	CHKD	James	SCALE 4:1 UNIT: mm
		APVD	Boye	SIZE: A3 SHEET: 1 OF 1 REV: A
CUSTOMER COPY				